1. General description

Planar Low V_F Schottky barrier rectifier encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- · Very low forward voltage
- High power capability due to clip-bond technology
- · Small and thin SMD plastic package

3. Applications

- · High efficiency DC-to-DC conversion
- · Low voltage rectification
- · Switch mode power supply
- · Freewheeling application
- · Reverse polarity protection
- OR-ing

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} \leq 174 °C		-	-	10	Α
V _R	reverse voltage	T _j = 25 °C		-	-	45	V
V _F	forward voltage	I _F = 10 A; pulsed; T _j = 25 °C	[1]	-	450	490	mV
I _R	reverse current	V _R = 45 V; pulsed; T _j = 25 °C	[1]	-	150	600	μΑ

^[1] Very short pulse, in order to maintain a stable junction temperature.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	Α	anode	5	
2	Α	anode		K F
3	K	cathode	[2]	aaa-009063
			CFP15B (SOT1289B)	



6. Ordering information

Table 3. Ordering information

Type number	Package	age				
	Name	Description	Version			
PMEG045V100EPE		plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	SOT1289B			

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG045V100EPE	045V
	100E

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	T _j = 25 °C		-	45	V
I _F	forward current	δ = 1; $T_{sp} \le 173 ^{\circ}\text{C}$		-	14	А
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 174 °C		-	10	Α
I _{FSM}	non-repetitive peak forward current	$t_p = 8.3 \text{ ms}$; half sine wave; $T_{j(init)} = 25 \text{ °C}$		-	300	Α
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	1.66	W
			[2]	-	2.15	W
Tj	junction temperature			-	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C

^[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

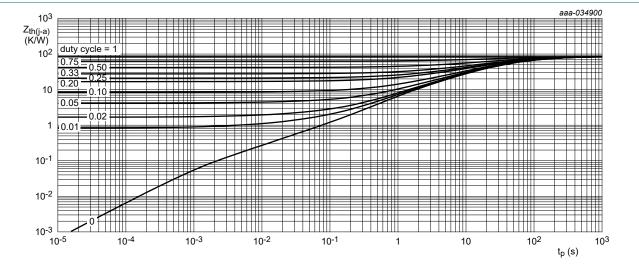
Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

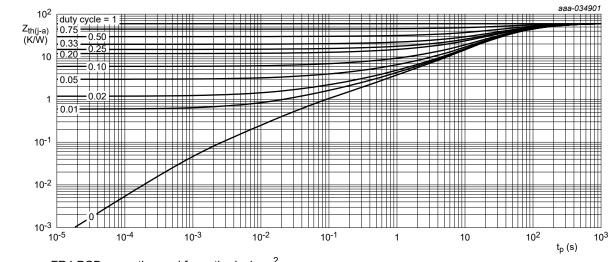
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R _{th(j-a)}	thermal resistance from	in free air	[1] [2]	-	-	90	K/W
jund	unction to ambient		[1] [3]	-	-	70	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point		[4]	-	-	3	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

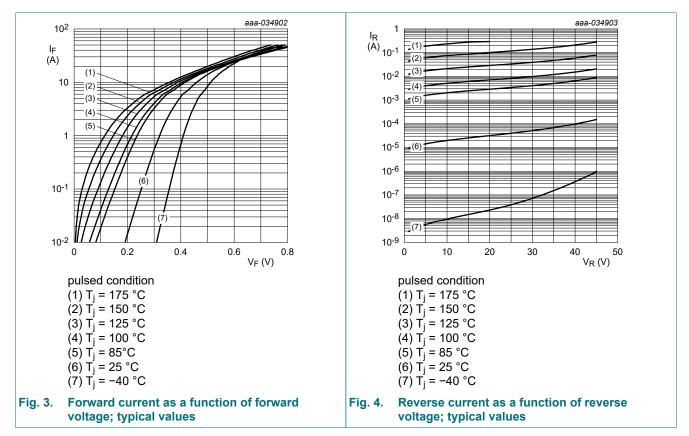
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 5 \text{ mA}$; pulsed; $T_j = 25 \text{ °C}$	[1]	45	-	-	V
V _F	forward voltage	I _F = 1 A; pulsed; T _j = 25 °C	[1]	-	320	360	mV
		I _F = 5 A; pulsed; T _j = 25 °C	[1]	-	390	430	mV
		I _F = 10 A; pulsed; T _j = 25 °C	[1]	-	450	490	mV
		I _F = 10 A; pulsed; T _j = -40 °C	[1]	-	510	570	mV
		I _F = 10 A; pulsed; T _j = 125 °C	[1]	-	390	460	mV
I _R	reverse current	V _R = 45 V; pulsed; T _j = 25 °C	[1]	-	150	600	μΑ
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C		-	1140	-	pF
		V _R = 10 V; f = 1 MHz; T _j = 25 °C		-	375	-	pF
t _{rr}	reverse recovery time step recovery	$I_F = 0.5 \text{ A}$; $I_R = 0.5 \text{ A}$; $I_{R(meas)} = 0.1 \text{ A}$; $T_j = 25 \text{ °C}$		-	36	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 100 \text{ A/}\mu\text{s}; I_F = 3 \text{ A}; V_R = 30 \text{ V};$ $T_j = 25 \text{ °C}$		-	19	-	ns
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}$; $dI_F/dt = 20 \text{ A/µs}$; $T_j = 25 \text{ °C}$		-	290	-	mV

[1] Very short pulse, in order to maintain a stable junction temperature.



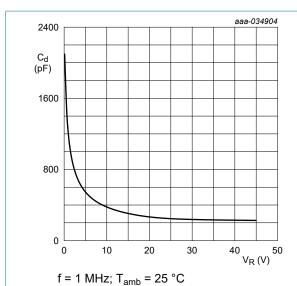
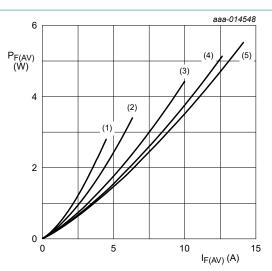
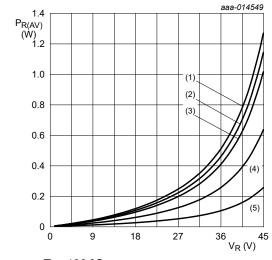


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



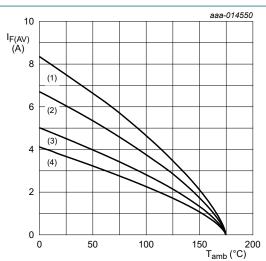
 $T_j = 100 \,^{\circ}\text{C}$ $(1) \, \delta = 0.1$ $(2) \, \delta = 0.2$ $(3) \, \delta = 0.5$ $(4) \, \delta = 0.8$ $(5) \, \delta = 1$

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



 $T_j = 100 \,^{\circ}\text{C}$ $(1) \, \delta = 1$ $(2) \, \delta = 0.9$ $(3) \, \delta = 0.8$ $(4) \, \delta = 0.5$ $(5) \, \delta = 0.2$

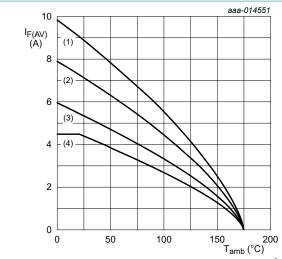
Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint $T_j = 175$ °C (1) $\delta = 1$; DC (2) $\delta = 0.5$; f = 20 kHz

(3) δ = 0.2; f = 20 kHz (4) δ = 0.1; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²

 $T_i = 175 \,{}^{\circ}\text{C}$

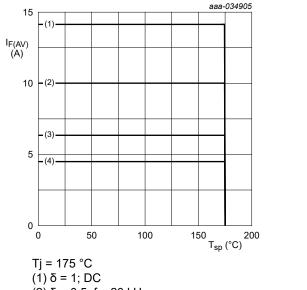
 $(1) \delta = 1$; DC

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Average forward current as a function of Fig. 9. ambient temperature; typical values

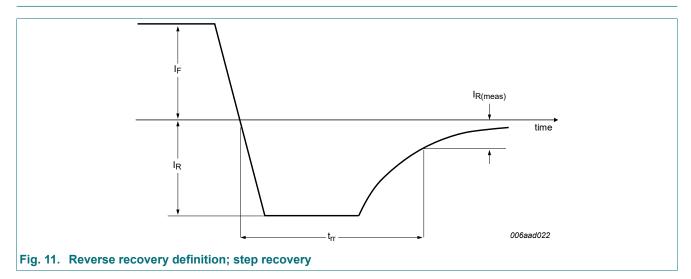


(2) $\delta = 0.5$; f = 20 kHz(3) $\delta = 0.2$; f = 20 kHz

 $(4) \delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

11. Test information



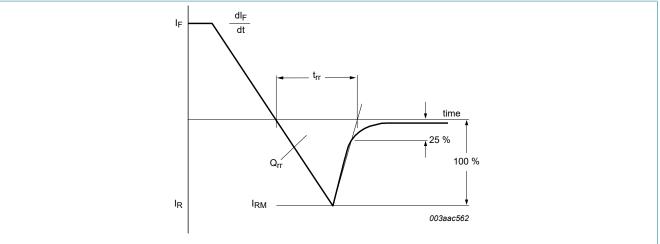


Fig. 12. Reverse recovery definition; ramp recovery

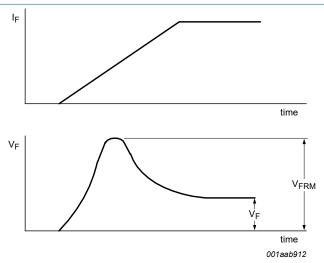


Fig. 13. Forward recovery definition

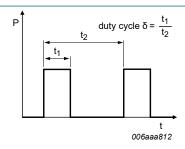


Fig. 14. Duty cycle definition

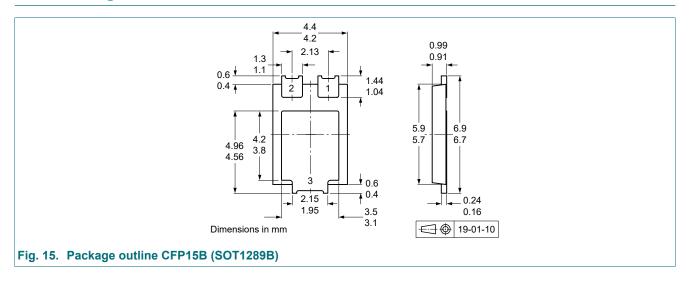
The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

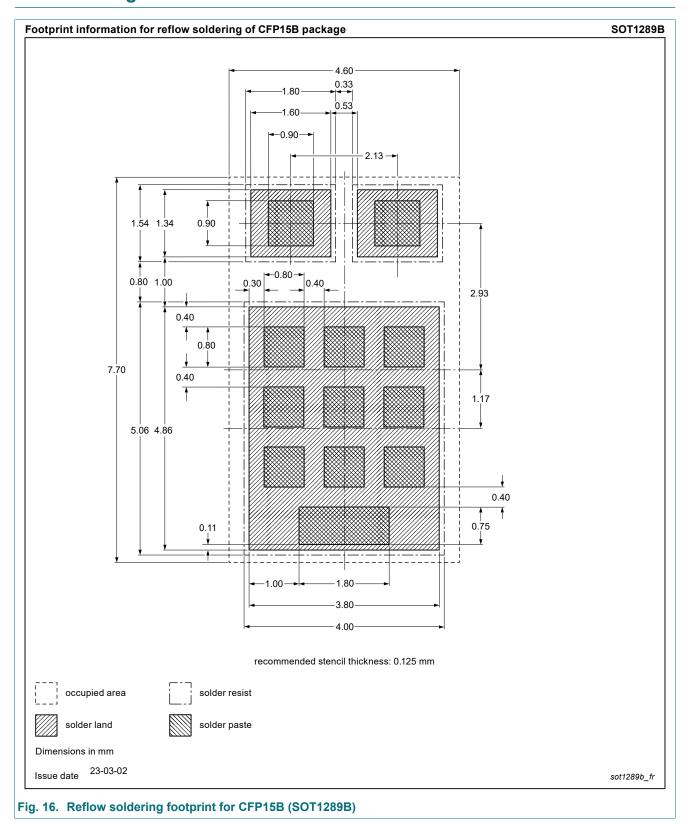
 $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_{M} \times \sqrt{\delta}$

with $I_{\mbox{\scriptsize RMS}}$ defined as RMS current.

12. Package outline



13. Soldering



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14. Revision history

Table 8. Revision history

Table 6. Revision mistory							
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes			
PMEG045V100EPE v.3	20240715	Product data sheet	-	PMEG045V100EPE v.2			
Modifications:	Reflow solder	Reflow soldering footprint: Stencil design for solder paste printing changed.					
PMEG045V100EPE v.2	20220718	Product data sheet	-	PMEG045V100EPE v.1			
PMEG045V100EPE v.1	20220524	Preliminary data sheet	-	-			

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15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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